

Product Features

- DC 5.5 GHz
- +15.5 dBm P1dB at 1 GHz
- +32 dBm OIP3 at 1 GHz
- 15 dB Gain at 1 GHz
- 4.0 dB Noise Figure at 2 GHz
- Available in lead-free / green SOT-363, SOT-86 and SOT-89 Package Styles
- Internally matched to $50 \ \Omega$

Applications

- Mobile Infrastructure
- CATV / DBS
- W-LAN / ISM
- RFID
- Defense / Homeland Security

Specifications⁽¹⁾

• Fixed Wireless

Parameter	Units	Min	Тур	Max
	1		Тур	
Operational Bandwidth	MHz	DC		5500
Test Frequency	MHz		1000	
Gain	dB		15	
Output P1dB	dBm		+15.4	
Output IP3 ⁽²⁾	dBm		+32	
Test Frequency	MHz		2000	
Gain	dB	12	14	18
Input Return Loss	dB		18	
Output Return Loss	dB		14	
Output P1dB	dBm	12	15	
Output IP3 ⁽²⁾	dBm		32	
Noise Figure	dB		4.0	
Device Voltage	V	3.5	3.9	4.3
Device Current	mA		45	

Test conditions unless otherwise noted: 25° C, Supply Voltage = +5 V, Rbias = 24.3 Ω, 50 Ω System.
3OIP measured with two tones at an output power of +2 dBm/tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule.

Absolute Maximum Rating

Parameter	Rating
Operating Case Temperature	-40 to +85 °C
Storage Temperature	-55 to +150 °C
Device Current	150 mA
RF Input Power (continuous)	+12 dBm
Junction Temperature	+250 °C

Operation of this device above any of these parameters may cause permanent damage

Product Description

The ECG006 is a general-purpose buffer amplifier that offers high dynamic range in a low-cost surface-mount package. At 1000 MHz, the ECG006 typically provides 15 dB of gain, +32 dBm Output IP3, and +15.5 dBm P1dB.

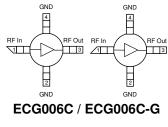
The ECG006 consists of Darlington pair amplifiers using the high reliability InGaP/GaAs HBT process technology and only requires DC-blocking capacitors, a bias resistor, and an inductive RF choke for operation. The device is ideal for wireless applications and is available in low-cost, surface-mountable plastic lead-free/green/RoHS-compliant SOT-363, SOT-86 and SOT-89 packages. All devices are 100% RF and DC tested.

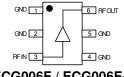
The broadband MMIC amplifier can be directly applied to various current and next generation wireless technologies such as GPRS, GSM, CDMA, and W-CDMA. In addition, the ECG006 will work for other various applications within the DC to 5.5 GHz frequency range such as CATV and fixed wireless.

Functional Diagram



ECG006B / ECG006B-G





ECG006F / ECG006F-G

Typical Performance ⁽³⁾

Parameter	Units	Typical						
Frequency	MHz	500	900	1900	2140			
S21	dB	15.5	15	14.2	14			
S11	dB	-20	-14	-17.4	-18			
S22	dB	-16	-13	-14.5	-15			
Output P1dB	dBm	+15.8	+15.4	+15	+15			
Output IP3 ⁽²⁾	dBm	+32	+32	+30	+30			
Noise Figure	dB	3.7	3.7	3.7	3.7			

3. Test conditions: T = 25° C, Supply Voltage = +5 V, Device Voltage = +3.9V, R_{bias} = 24.3 Ω, 50 Ω System.

Ordering Information

Part No.	Description
ECG006B*	InGaP HBT Gain Block
	(lead-tin SOT-89 Pkg)
ECG006B-G	InGaP HBT Gain Block
	(lead-free/green/RoHS-compliant SOT-89 Pkg)
ECG006C*	InGaP HBT Gain Block
	(lead-tin SOT-86 Pkg) InGaP HBT Gain Block
ECG006C-G	(lead-free/green/RoHS-compliant SOT-86 Pkg)
	InGaP HBT Gain Block
ECG006F*	(lead-tin SOT-363 Pkg)
	InGaP HBT Gain Block
ECG006F-G	(lead-free/green/RoHS-compliant SOT-363 Pkg)
ECG006B-PCB	700 - 2400 MHz Fully Assembled Eval. Board
ECG006C-PCB	700 - 2400 MHz Fully Assembled Eval. Board
ECG006F-PCB	700 - 2400 MHz Fully Assembled Eval. Board
	2
* This package is being phas	ed out in favor of the green package type which is backwards compatible fo

existing designs.

Specifications and information are subject to change without notice



3.60 3.80 4.00 4.20 4.40

3.00 3.20 3.40



1500

2000

1000

500

Typical Device RF Performance Supply Bias = +5 V, R_{bias} = 24.3 Ω , I_{cc} = 45 mA

Frequency	MHz	100	500	900	1900	2140	2400	3500	5800
S21	dB	15.3	15.2	15.1	14.5	14.3	14.1	13.9	10.2
S11	dB	-20	-18	-14	-17	-18	-20	-17	-12.5
S22	dB	-29	-16	-13	-14	-14	-15	-15	-9.5
Output P1dB	dBm	+15.8	+15.4	+15.2	+15.0	+14.9	+14.6	+14	
Output IP3	dBm	+31	+31.5	+32	+30	+30	+29.6		
Noise Figure	dB	3.8	3.7	3.6	3.6	3.6	3.6		

1. Test conditions: $T = 25^{\circ}$ C, Supply Voltage = +5 V, Device Voltage = +3.9 V, Rbias = 24.3 Ω , Icc = 45 mA typical, 50 Ω System.

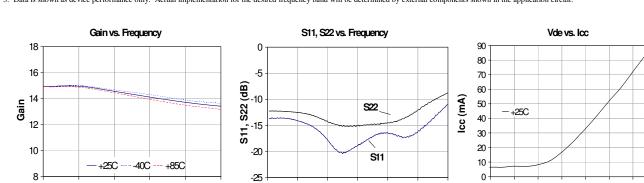
3000

0

1

2500

30IP measured with two tones at an output power of +2 dBm/tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the 30IP using a 2:1 rule.
Data is shown as device performance only. Actual implementation for the desired frequency band will be determined by external components shown in the application circuit.



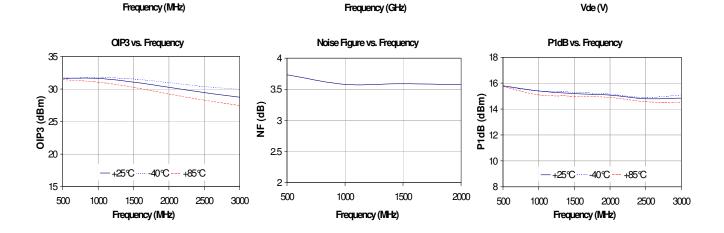
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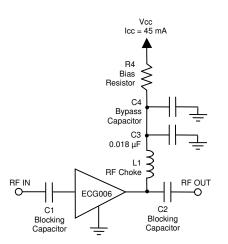
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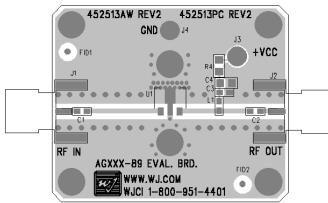




Recommended Application Circuit



ECG006B-PCB

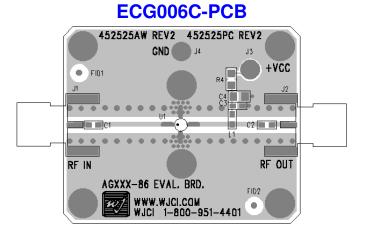


Recommended Component Values

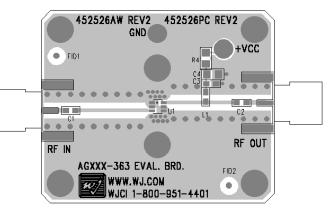
Reference	Frequency (MHz)							
Designator	50	500	900	1900	2200	2500	3500	
L1	820 nH	220 nH	68 nH	27 nH	22 nH	18 nH	15 nH	
C1, C2, C4	.018 µF	1000 pF	100 pF	68 pF	68 pF	56 pF	39 pF	

The proper values for the components are dependent upon the intended frequency of operation.
The following values are contained on the evaluation board to achieve optimal broadband performance:

Ref. Desig.	Value / Type	Size
L1	39 nH wirewound inductor	0603
C1, C2	56 pF chip capacitor	0603
C3	0.018 µF chip capacitor	0603
C4	Do Not Place	
R4	24.3Ω 1% tolerance	0805



ECG006F-PCB



Recommended Bias Resistor Values

Supply Voltage	R1 value	Size
5 V	24.4 ohms	0805
6 V	46.7 ohms	0805
8 V	91 ohms	1210
9 V	113 ohms	1210
10 V	136 ohms	2010
12 V	180 ohms	2010

The proper value for R1 is dependent upon the supply voltage and allows for bias stability over temperature. WJ recommends a minimum supply bias of +5 V. A 1% tolerance resistor is recommended.

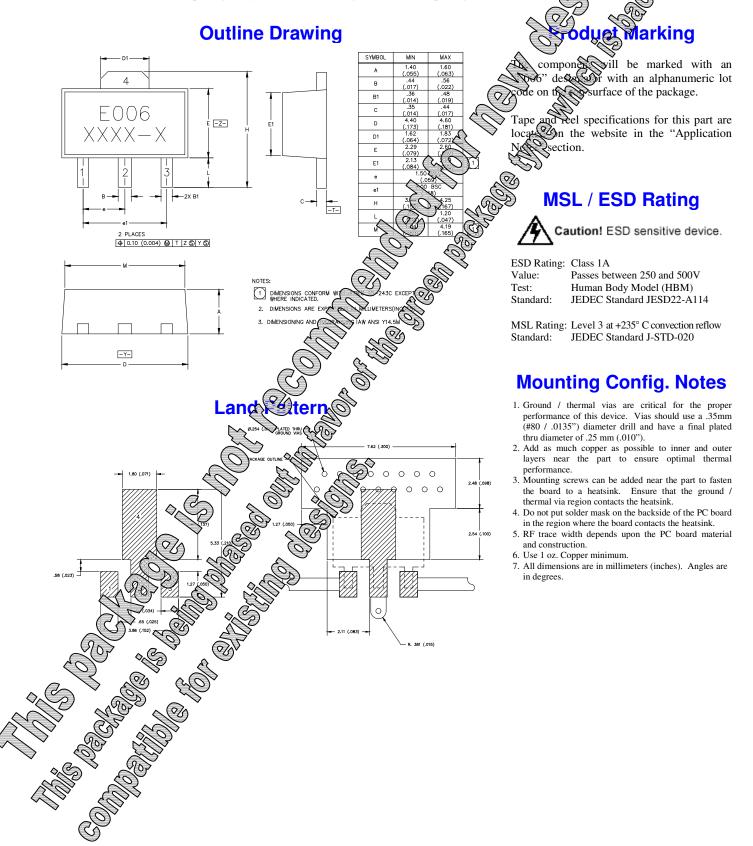


The Communications Edge

A Information

ECG006B (SOT-89 Package) Mechanical Information

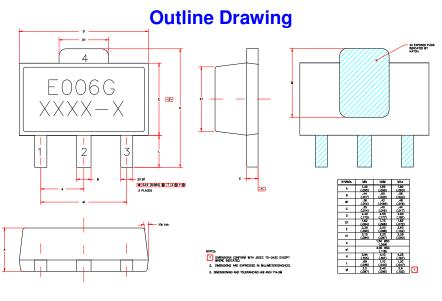
This package may contain lead-bearing materials. The plating material on the lead in the



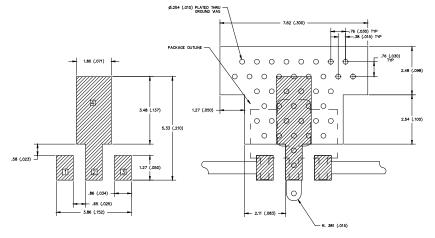


ECG006B-G (Green / Lead-free SOT-89 Package) Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the leads is NiPdAu.



Land Pattern



Product Marking

The component will be marked with an "E006G" designator with an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating

Caution! ESD sensitive device.

ESD Rating: Class 1A Value: Passes between 250 and 500V Test: Human Body Model (HBM) Standard: JEDEC Standard JESD22-A114

MSL Rating: Level 3 at +260° C convection reflow Standard: JEDEC Standard J-STD-020

Mounting Config. Notes

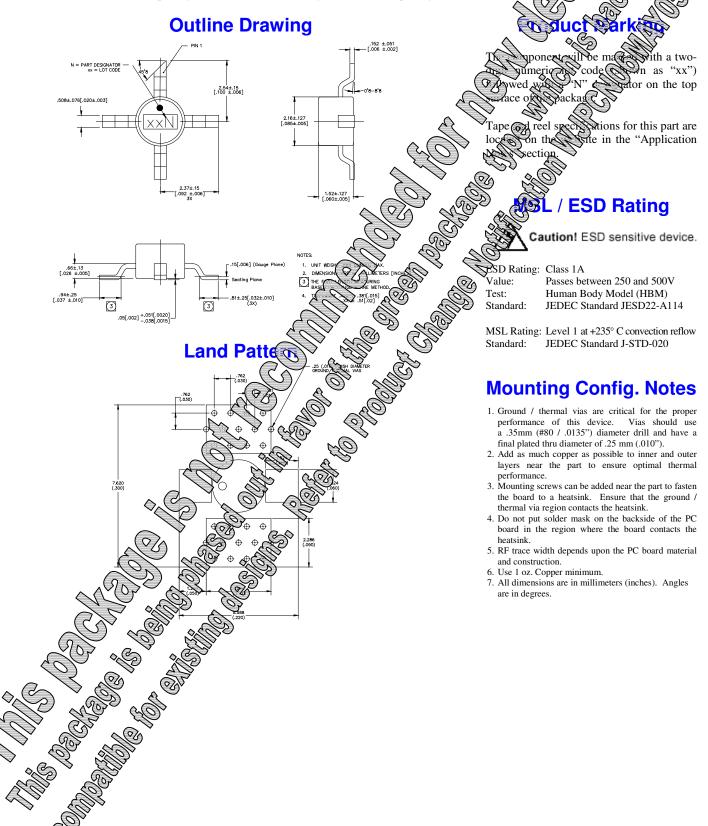
- Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.





ECG006C (SOT-86 Package) Mechanical Informa

This package may contain lead-bearing materials. The plating material on the leads





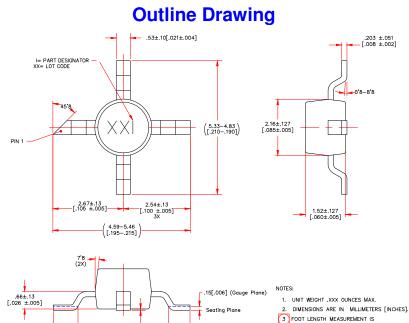
.94±.25 [.037 ±.010]

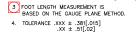
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.05[.002] +.051[.0020] -.038[.0015] **Product Information**

ECG006C-G (Green / Lead-free Sot-86 Package) Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matte tin over copper.

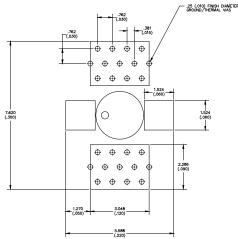




Land Pattern

3

.81±.25[.032±.010] (3X)



Product Marking

The component will be marked with a twodigit numeric lot code (shown as "XX") followed with a "I" designator on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating

Caution! ESD sensitive device.

ESD Rating:	Class 1A
Value:	Passes between 250 and 500V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

MSL Rating: Level 3 at +260° C convection reflow Standard: JEDEC Standard J-STD-020

Mounting Config. Notes

- Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.



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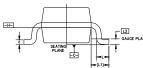
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ECG006F (SOT-363 Package) Mechanical Information

This package may contain lead-bearing materials. The plating material on the leads

Outline Drawing





- TERS (INCHES) 3
- \bullet

3" " " "

34 4215 CA-B 20 3 = PART DESIGNATOR -A--0 5 -D-E/2 E1/2 300 中 🕇 E 2X 255CD 2 5 ==--(6X)b ∰60∭0|A--B|D -B-TOP VIEW

SIDE VIEW

6

6

.and

two-'XX") on the top

for this part are in the "Application

ESD Rating

ution! ESD sensitive device.

Class 1A ating: Passes between 250 and 500V Human Body Model (HBM) JEDEC Standard JESD22-A114 tandard:

MSL Rating: Level 3 at +235° C convection reflow JEDEC Standard J-STD-020 Standard:

Mounting Config. Notes

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- 3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PC board material and construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.

Specifications and information are subject to change without notice

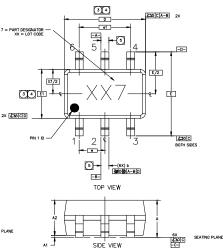


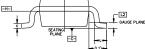
ECG006F-G (Green / Lead-free SOT-363 Package) Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the leads is annealed matte tin over copper.

Outline Drawing



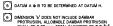


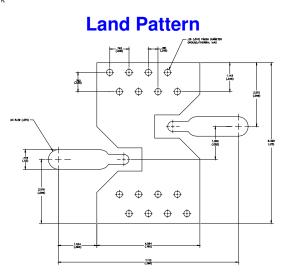




DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1194, PACKAGE CONFORMS TO JEDEC MO-203, ISSUE B, DIMENSIONS ARE IN MULTIMETER CONFORMATION OF THE STATE RS (INCHES)

- 3 DIME D DOES NOT INCLUDE MOLD FLAS
- € OP MAY BE SMALLER THAN THE PACKAGE RAINED AT THE OUTERMOST E E OF MOLD FLASH, THE BAR BI ASH, BUT INCLUDING ANY MISI TOM OF THE PLASTIC





Product Marking

The component will be marked with a twodigit numeric lot code (shown as "XX") followed with a "7" designator on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating

Caution! ESD sensitive device.

ESD Rating:	Class 1A
Value:	Passes between 250 and 500V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

MSL Rating: Level 3 +260° C convection reflow JEDEC Standard J-STD-020 Standard:

Mounting Config. Notes

- 1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near 2. the part to ensure optimal thermal performance. Mounting screws can be added near the part to fasten the
- 3 board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- Do not put solder mask on the backside of the PC board in the
- region where the board contacts the heatsink. RF trace width depends upon the PC board material and 5. construction.
- 6. Use 1 oz. Copper minimum.
- 7. All dimensions are in millimeters (inches). Angles are in degrees.



Typical Device S-Parameters – ECG006B / ECG006B-G

S-Parameters ($V_{device} = +3.9 \text{ V}$, $I_{CC} = 45 \text{ mA}$, T = 25°C, calibrated to device leads)									
Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)	
50	-16.18	-2.18	15.76	178.02	-18.89	-0.38	-14.36	-2.29	
500	-16.13	-22.13	15.57	160.12	-18.77	-2.87	-14.40	-26.41	
1000	-15.97	-44.58	15.21	141.76	-18.46	-5.33	-14.15	-51.57	
1500	-15.79	-68.38	14.80	124.56	-17.94	-9.45	-13.78	-77.30	
2000	-15.34	-96.24	14.57	108.50	-17.29	-14.37	-13.23	-104.15	
2500	-14.99	-124.42	14.34	91.11	-16.69	-21.48	-12.79	-131.75	
3000	-14.73	-153.90	14.02	74.20	-16.16	-29.16	-12.22	-160.58	
3500	-14.29	174.59	13.65	56.77	-15.76	-38.37	-11.63	170.65	
4000	-13.38	141.41	13.22	39.56	-15.49	-47.75	-10.44	143.61	
4500	-11.80	110.87	12.66	22.19	-15.29	-57.59	-9.04	117.68	
5000	-9.66	85.53	12.00	5.48	-15.28	-68.56	-7.50	96.34	
5500	-7.85	63.77	11.20	-10.89	-15.43	-79.10	-6.12	76.71	
6000	-6.37	47.01	10.36	-26.75	-15.69	-89.87	-4.95	59.58	

Typical Device S-Parameters – ECG006C / ECG006C-F

S-Parameters ($V_{\text{device}} = +3.9 \text{ V}$, $I_{\text{CC}} = 45 \text{ mA}$, $T = 25^{\circ}\text{C}$, calibrated to device leads)									
Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)	
50	-13.66	-1.22	15.30	178.47	-18.67	-0.33	-12.25	-1.92	
500	-13.64	-13.39	15.23	164.32	-18.59	0.29	-12.33	-20.62	
1000	-14.11	-23.99	15.01	149.00	-18.38	0.78	-12.52	-41.41	
1500	-15.20	-35.45	14.72	134.06	-17.99	0.29	-13.08	-62.51	
2000	-17.86	-52.47	14.44	119.89	-17.52	-0.93	-14.31	-82.78	
2500	-20.46	-93.43	14.06	105.18	-17.12	-3.33	-15.20	-99.71	
3000	-18.86	-135.97	13.53	91.27	-16.59	-6.24	-15.01	-124.98	
3500	-17.20	-158.47	12.99	77.75	-16.21	-10.91	-14.89	-157.99	
4000	-16.45	-171.80	12.38	65.03	-15.93	-15.16	-14.50	170.24	
4500	-17.31	166.84	11.76	52.68	-15.73	-19.74	-13.75	147.52	
5000	-16.22	136.42	11.25	40.65	-15.52	-24.35	-12.08	133.59	
5500	-13.68	110.91	10.56	28.09	-15.42	-29.98	-10.21	119.31	
6000	-11.01	97.79	9.95	17.28	-15.43	-34.96	-8.73	106.39	

Typical Device S-Parameters – ECG006F / ECG006F-G

S-Parameters ($V_{device} = +3.9 \text{ V}$, $I_{CC} = 45 \text{ mA}$, $T = 25^{\circ}$ C, calibrated to device leads)								
Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
50	-16.22	-0.52	15.76	178.32	-18.82	-0.82	-14.16	-2.06
500	-14.87	-18.97	15.63	165.77	-18.87	1.49	-12.83	-24.91
1000	-16.45	-51.46	15.51	151.31	-18.40	1.44	-14.19	-55.98
1500	-16.41	-95.69	15.22	137.15	-18.07	0.35	-14.59	-93.37
2000	-14.08	-118.65	14.79	123.39	-17.74	-1.31	-13.52	-120.99
2500	-12.50	-114.48	14.48	112.93	-17.16	-2.57	-13.05	-122.53
3000	-12.18	-126.96	14.14	100.74	-16.80	-4.49	-12.19	-138.80
3500	-11.70	-139.53	13.94	88.52	-16.16	-8.66	-11.93	-159.41
4000	-10.97	-158.51	13.57	75.28	-15.72	-12.48	-11.00	174.63
4500	-10.24	178.62	13.03	62.14	-15.50	-19.07	-9.10	151.63
5000	-9.06	161.58	12.33	51.12	-15.19	-24.71	-7.50	139.14
5500	-8.32	150.77	11.60	42.08	-15.22	-28.00	-6.87	136.14
6000	-7.84	140.56	10.95	33.72	-15.14	-30.97	-6.78	137.51

Device S-parameters are available for download off of the website at: http://www.wj.com